



DMP6110SSDQ

Product Summary

BV _{DSS}	R _{DS(ON)} Max	Ι _D T _A = +25°C
-60V	$105m\Omega @ V_{GS} = -10V$	-3.3A
-007	$130m\Omega @ V_{GS} = -4.5V$	-3.0A

Description and Applications

This MOSFET is designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Engine Management Systems
- Body Control Electronics
- DC-DC Converters

Features

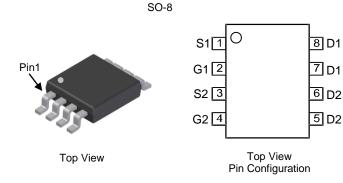
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)

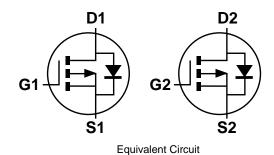
P-CHANNEL ENHANCEMENT MODE MOSFET

- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.074 grams (Approximate)





Ordering Information (Note 5)

Part Number	Case	Packaging
DMP6110SSDQ-13	SO-8	2,500/Tape & Reel
DMP6110SSDQ-13		2,500/Tape & Reel

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

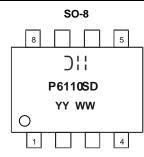
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product_compliance_definitions.html.

5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

Notes:



):' = Manufacturer's Marking
P6110SD = Product Type Marking Code
YYWW = Date Code Marking
YY = Year (ex: 16 = 2016)
WW = Week (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V _{DSS}	-60	V	
Gate-Source Voltage		V _{GSS}	±20	V
Continuous Duris Current (Nate 7))/ 40)/	$T_{C} = +25^{\circ}C$ $T_{C} = +70^{\circ}C$	ID	-7.8 -6.3	A
Continuous Drain Current (Note 7) V _{GS} = -10V	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	ID	-3.3 -2.7	A
Pulsed Drain Current (380µs Pulse, 1% Duty Cycle)		I _{DM}	-24	A
Maximum Continuous Body Diode Forward Current (Note 7)	ls	-1.8	A	
Avalanche Current (Note 10) L = 0.1mH		I _{AS}	-19	А
Avalanche Energy (Note 10) L = 0.1mH		E _{AS}	18	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Notes 6 & 8)	T _A = +25°C		1.2	w
Total Power Dissipation (Notes 6 & 6)	T _A = +70°C	PD	0.9	
Total Power Dissipation (Notes 6 & 9)	T _A = +25°C		1.2	
Thermal Resistance, Junction to Ambient (Notes 6 & 8)	Steady State		104	°C/W
memar Resistance, Junction to Ambient (Notes 6 & 6)	t<10s	$R_{\theta JA}$	45	
Thermal Resistance, Junction to Ambient (Notes 6 & 9)	Steady State		100	
Total Power Dissipation (Notes 7 & 8)	T _A = +25°C		1.7	W
Total Fower Dissipation (Notes 7 & 8)	T _A = +70°C	PD	1.1	
Total Power Dissipation (Notes 7 & 9)	$T_A = +25^{\circ}C$		1.8	
Thermal Resistance, Junction to Ambient (Notes 7 & 8)	Steady State		74	80AM
Thermal Resistance, Junction to Ambient (Notes 7 & 0)	t<10s	$R_{ ext{ heta}JA}$	37	
Thermal Resistance, Junction to Ambient (Notes 7 & 9) Steady State			71	°C/W
Thermal Resistance, Junction to Case (Notes 7 & 8)		$R_{\theta JC}$	15	
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

Notes: 6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

7. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

8. For a dual device with one active die.

9. For a device with two active die running at equal power.

10. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25^{\circ}C$.

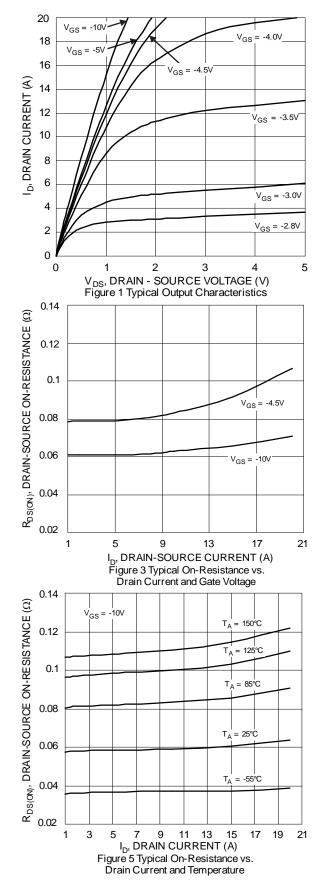


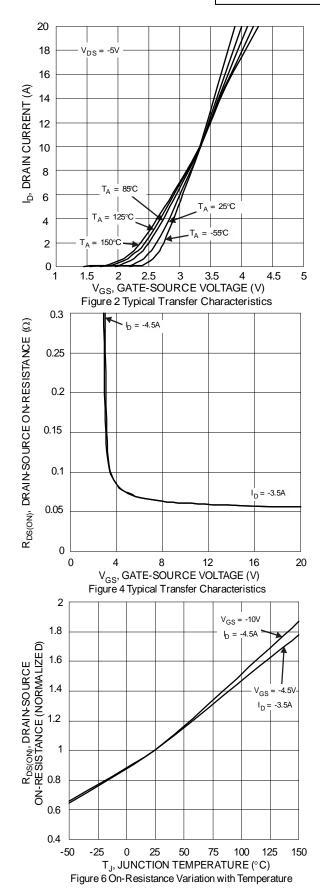
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 11)	.		- 71-		•••••		
Drain-Source Breakdown Voltage	BV _{DSS}	-60			V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}			-1	μA	$V_{DS} = -48V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	100	nA	$V_{GS} = \pm 16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 11)							
Gate Threshold Voltage	V _{GS(TH)}	-1		-3	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance			80	105	mΩ	V _{GS} = -10V, I _D = -4.5A	
Static Dialit-Source Off-Resistance	R _{DS(ON)}		95	130	11122	V _{GS} = -4.5V, I _D =-3.5A	
Diode Forward Voltage	V _{SD}		-0.7	-1.2	V	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 12)							
Input Capacitance	CISS	_	969		pF		
Output Capacitance	C _{OSS}		57		рF	$V_{DS} = -30V, V_{GS} = 0V, f = 1.0MHz$	
Reverse Transfer Capacitance	C _{RSS}		44		pF		
Gate Resistance	R _G		13.7		Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V _{GS} = -4.5V)	Q _G		8.2		nC	V _{DS} = -30V, I _D = -12A	
Total Gate Charge (V _{GS} = -10V)	Q_{G}	_	17.2	_	nC		
Gate-Source Charge	Q _{GS}	_	3.0	_	nC	$V_{DS} = -30V, I_{D} = -12A$	
Gate-Drain Charge	Q_{GD}	_	3.1	_	nC		
Turn-On Delay Time	t _{D(ON)}	_	4.4		ns		
Turn-On Rise Time	t _R	_	23	_	ns	$V_{GS} = -10V, V_{DS} = -30V,$	
Turn-Off Delay Time	t _{D(OFF)}		34		ns	$R_{GEN} = 3\Omega$, $I_{D} = -12A$	
Turn-Off Fall Time	t _F		42		ns		
Body Diode Reverse Recovery Time	t _{RR}	_	13.2		ns	L 124 di/dt 1004/up	
Body Diode Reverse Recovery Charge	Q _{RR}		6.18		nC	I _S = -12A, di/dt = 100A/μs	

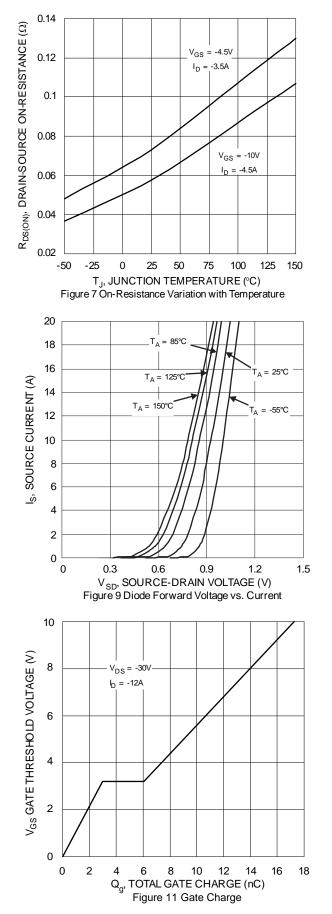
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing. Notes:

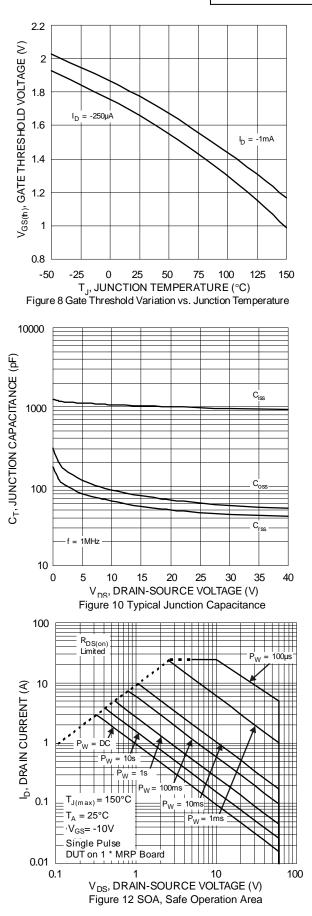






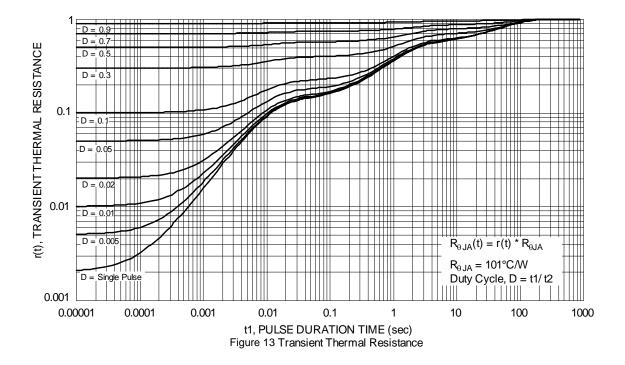














Тур

1.45

0.15

0.40

0.20

4.90

6.00

3.85

3.90

1.27

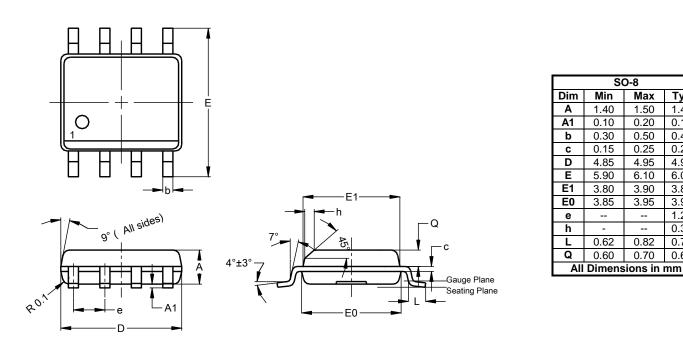
0.35

0.72

0.65

Package Outline Dimensions

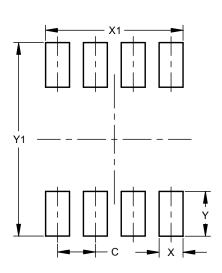
Please see http://www.diodes.com/package-outlines.html for the latest version.



SO-8

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



SO-8

Dimensions	Value (in mm)
С	1.27
Х	0.802
X1	4.612
Y	1.505
Y1	6.50



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